BCP68; BC868; BC68PA

20 V, 2 A NPN medium power transistors

Rev. 8 — 18 October 2011 Product data sheet

1. Product profile

1.1 General description

NPN medium power transistor series in Surface-Mounted Device (SMD) plastic packages.

Table 1. Product overview

Type number[1]	Package			PNP complement
	NXP	JEITA	JEDEC	
BCP68	SOT223	SC-73	-	BCP69
BC868	SOT89	SC-62	TO-243	BC869
BC68PA	SOT1061	-	-	BC69PA

[1] Valid for all available selection groups.

1.2 Features and benefits

- High current
- Two current gain selections
- High power dissipation capability
- Exposed heatsink for excellent thermal and electrical conductivity (SOT89, SOT1061)
- Leadless very small SMD plastic package with medium power capability (SOT1061)
- AEC-Q101 qualified

1.3 Applications

- Linear voltage regulators
- Low-side switches
- Battery-driven devices
- Power management
- MOSFET drivers
- Amplifiers

1.4 Quick reference data

Table 2. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CEO}	collector-emitter voltage	open base	-	-	20	V
I_C	collector current		-	-	2	A
I_{CM}	peak collector current	single pulse; $t_p \leq 1$ ms	-	-	3	A

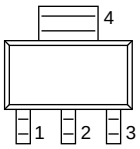
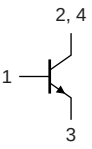
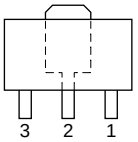
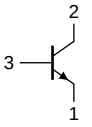
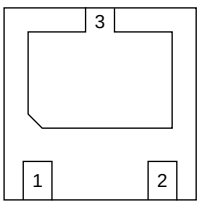
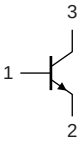
Table 2. Quick reference data *...continued*

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
h_{FE}	DC current gain	V_{CE} = 1 V; I_C = 500 mA	[1]	85	-	375	
	h_{FE} selection -25	V_{CE} = 1 V; I_C = 500 mA	[1]	160	-	375	

[1] Pulse test: $t_p \leq 300\ \mu s$; $\delta = 0.02$.

2. Pinning information

Table 3. Pinning

Pin	Description	Simplified outline	Graphic symbol
SOT223			
1	base		 sym016
2	collector		
3	emitter		
4	collector		
SOT89			
1	emitter		 sym042
2	collector		
3	base		
SOT1061			
1	base	 Transparent top view	 sym021
2	emitter		
3	collector		

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3. Ordering information

Table 4. Ordering information

Type number[1]	Package		
	Name	Description	Version
BCP68	SC-73	plastic surface-mounted package with increased heatsink; 4 leads	SOT223
BC868	SC-62	plastic surface-mounted package; exposed die pad for good heat transfer; 3 leads	SOT89
BC68PA	HUSON3	plastic thermal enhanced ultra thin small outline package; no leads; 3 terminals; body 2 × 2 × 0.65 mm	SOT1061

[1] Valid for all available selection groups.

4. Marking

Table 5. Marking codes

Type number	Marking code
BCP68	BCP68
BCP68-25	BCP68/25
BC868	CAC
BC868-25	CDC
BC68PA	AR
BC68-25PA	AS

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5. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{CBO}	collector-base voltage	open emitter		-	32	V
V_{CEO}	collector-emitter voltage	open base		-	20	V
V_{EBO}	emitter-base voltage	open collector		-	5	V
I_C	collector current			-	2	A
I_{CM}	peak collector current	single pulse; $t_p \leq 1$ ms		-	3	A
I_B	base current			-	0.4	A
I_{BM}	peak base current	single pulse; $t_p \leq 1$ ms		-	0.4	A
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C				
	BCP68		[1]	-	0.65	W
			[2]	-	1.00	W
			[3]	-	1.35	W
	BC868		[1]	-	0.50	W
			[2]	-	0.95	W
			[3]	-	1.35	W
	BC68PA		[1]	-	0.42	W
			[2]	-	0.83	W
			[3]	-	1.10	W
			[4]	-	0.81	W
			[5]	-	1.65	W
T_j	junction temperature			-	150	°C
T_{amb}	ambient temperature			−55	+150	°C
T_{stg}	storage temperature			−65	+150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1 cm^2.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 6 cm^2.

[4] Device mounted on an FR4 PCB, 4-layer copper, tin-plated and standard footprint.

[5] Device mounted on an FR4 PCB, 4-layer copper, tin-plated, mounting pad for collector 1 cm^2.

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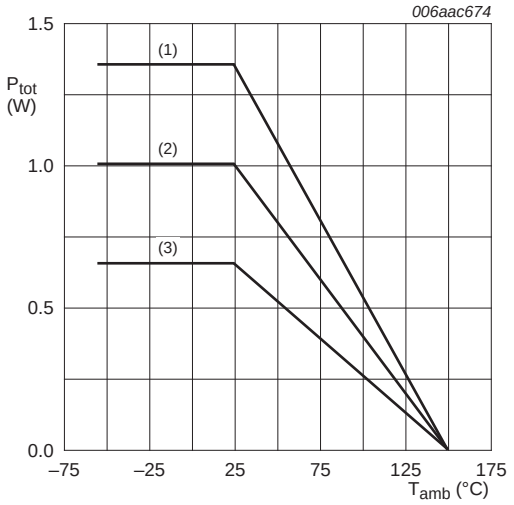
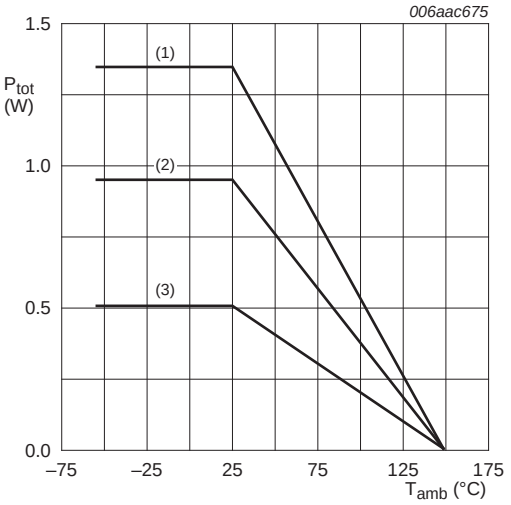


(1) FR4 PCB, mounting pad for collector 6 cm^2

(2) FR4 PCB, mounting pad for collector 1 cm^2

(3) FR4 PCB, standard footprint

Fig 1. Power derating curves SOT223

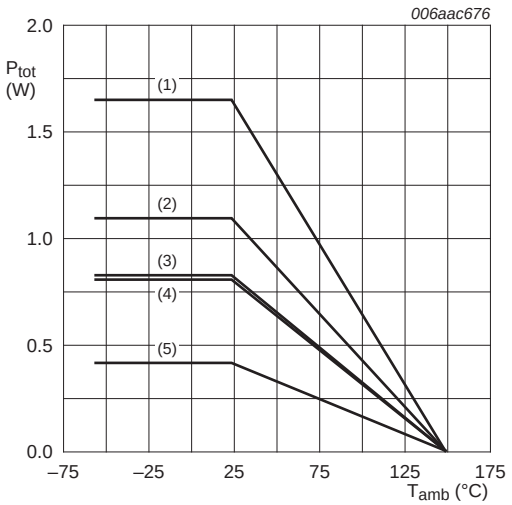


(1) FR4 PCB, mounting pad for collector 6 cm^2

(2) FR4 PCB, mounting pad for collector 1 cm^2

(3) FR4 PCB, standard footprint

Fig 2. Power derating curves SOT89



(1) FR4 PCB, 4-layer copper, mounting pad for collector 1 cm^2

(2) FR4 PCB, single-sided copper, mounting pad for collector 6 cm^2

(3) FR4 PCB, single-sided copper, mounting pad for collector 1 cm^2

(4) FR4 PCB, 4-layer copper, standard footprint

(5) FR4 PCB, single-sided copper, standard footprint

Fig 3. Power derating curves SOT1061

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6. Thermal characteristics

Table 7. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air					
	BCP68		[1]	-	-	192	K/W
			[2]	-	-	125	K/W
			[3]	-	-	93	K/W
	BC868		[1]	-	-	250	K/W
			[2]	-	-	132	K/W
			[3]	-	-	93	K/W
	BC68PA		[1]	-	-	298	K/W
			[2]	-	-	151	K/W
			[3]	-	-	114	K/W
			[4]	-	-	154	K/W
			[5]	-	-	76	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point						
	BCP68			-	-	16	K/W
	BC868			-	-	16	K/W
	BC68PA			-	-	20	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1 cm^2.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 6 cm^2.

[4] Device mounted on an FR4 PCB, 4-layer copper, tin-plated and standard footprint.

[5] Device mounted on an FR4 PCB, 4-layer copper, tin-plated, mounting pad for collector 1 cm^2.

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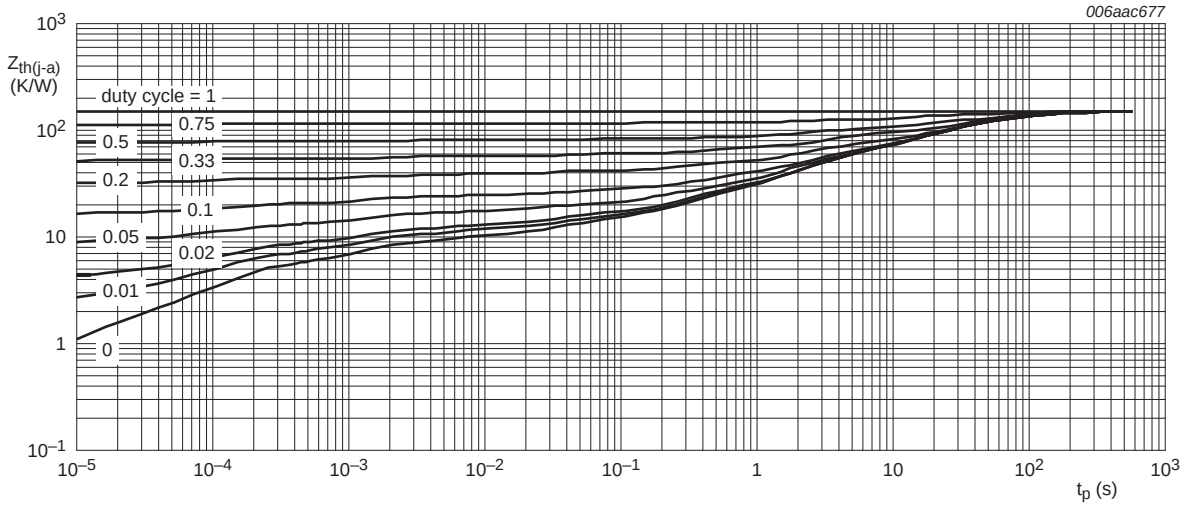
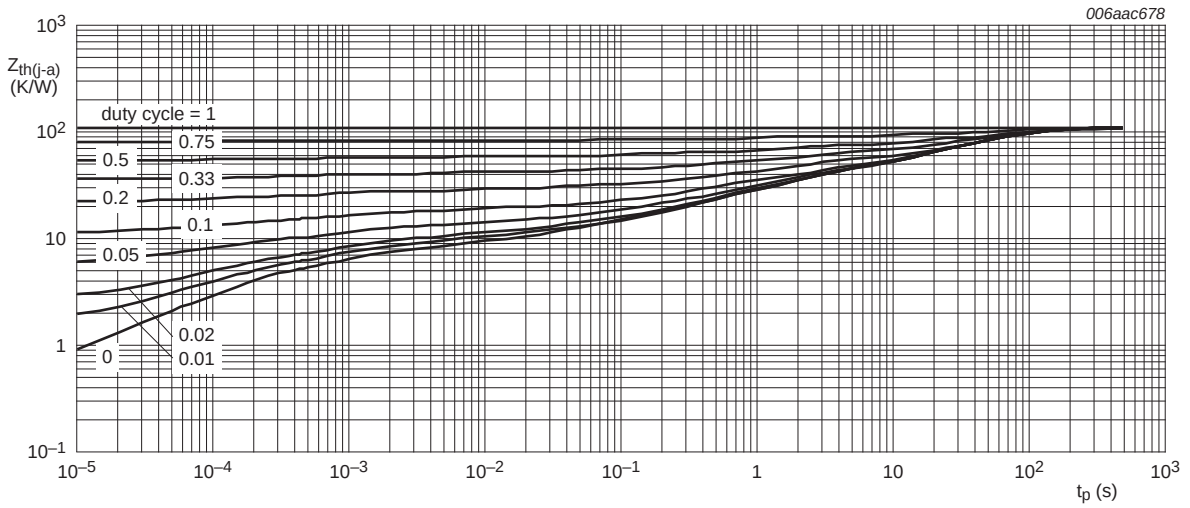


FR4 PCB, standard footprint

Fig 4. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT223; typical values



FR4 PCB, mounting pad for collector 1 cm^2

Fig 5. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT223; typical values

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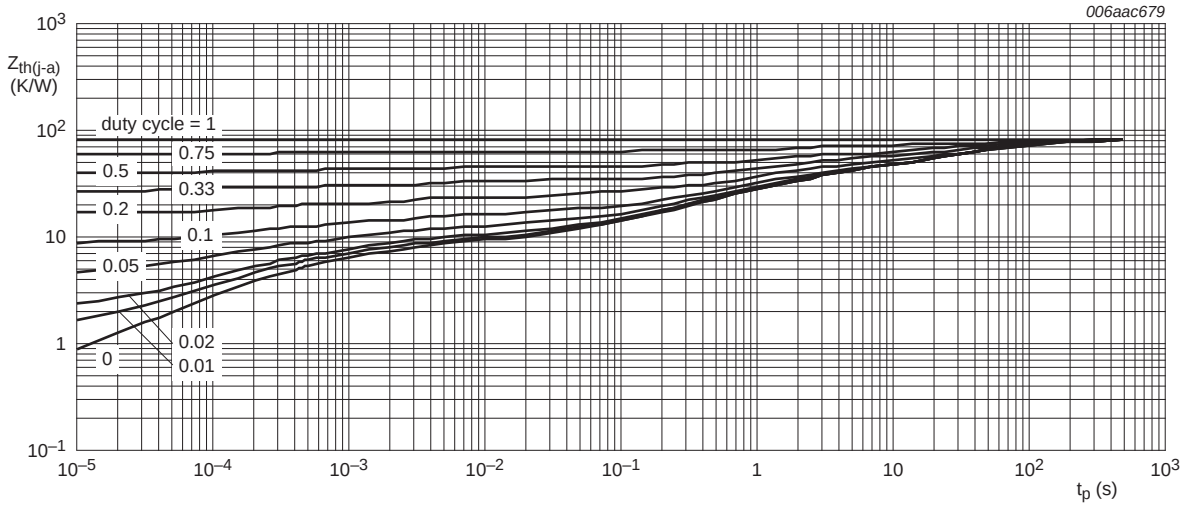
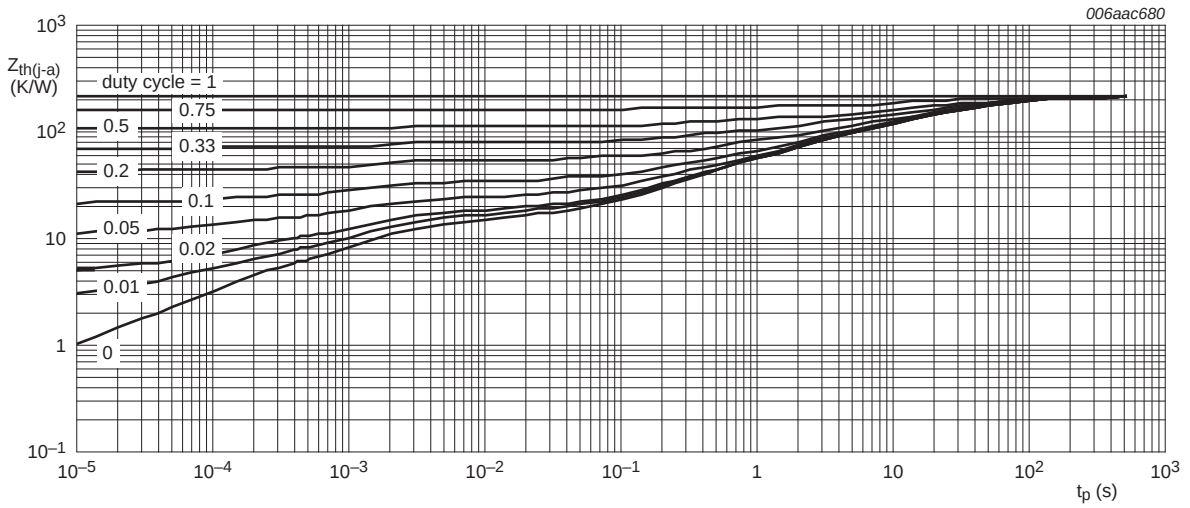


FR4 PCB, mounting pad for collector 6 cm^2

Fig 6. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT223; typical values



FR4 PCB, standard footprint

Fig 7. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT89; typical values

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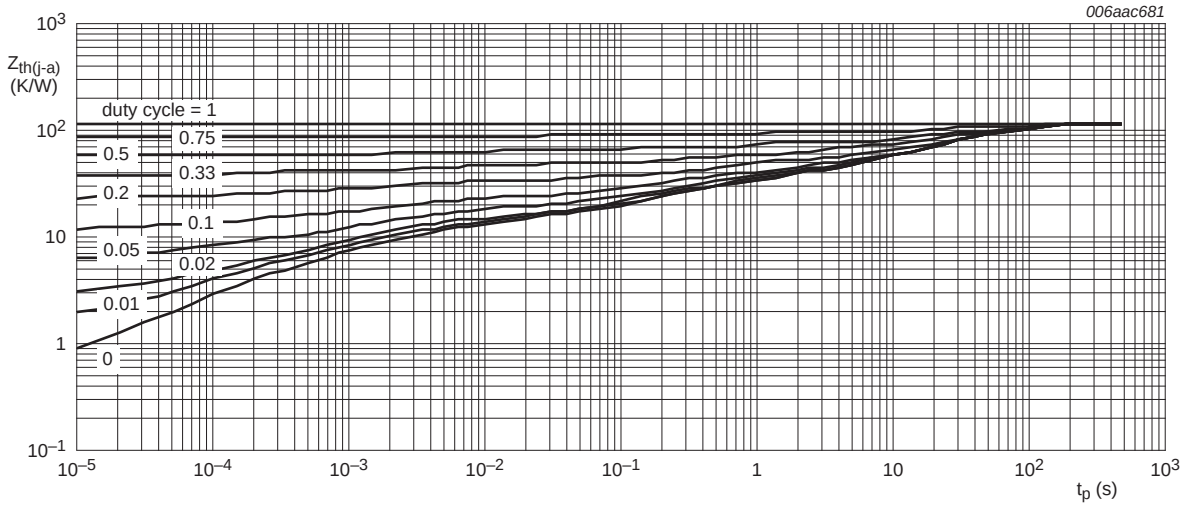
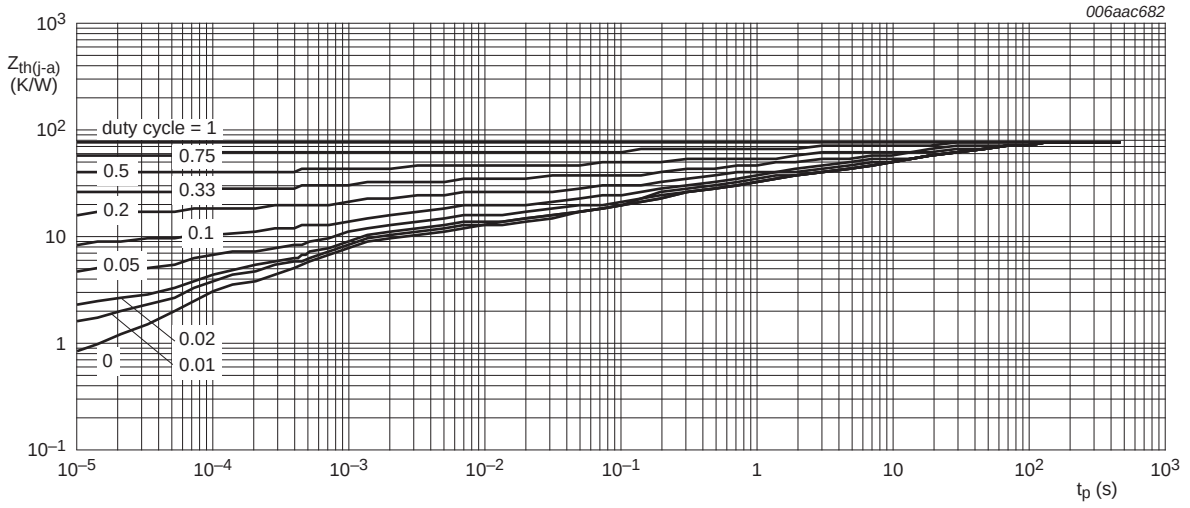


FR4 PCB, mounting pad for collector 1 cm^2

Fig 8. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT89; typical values



FR4 PCB, mounting pad for collector 6 cm^2

Fig 9. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT89; typical values

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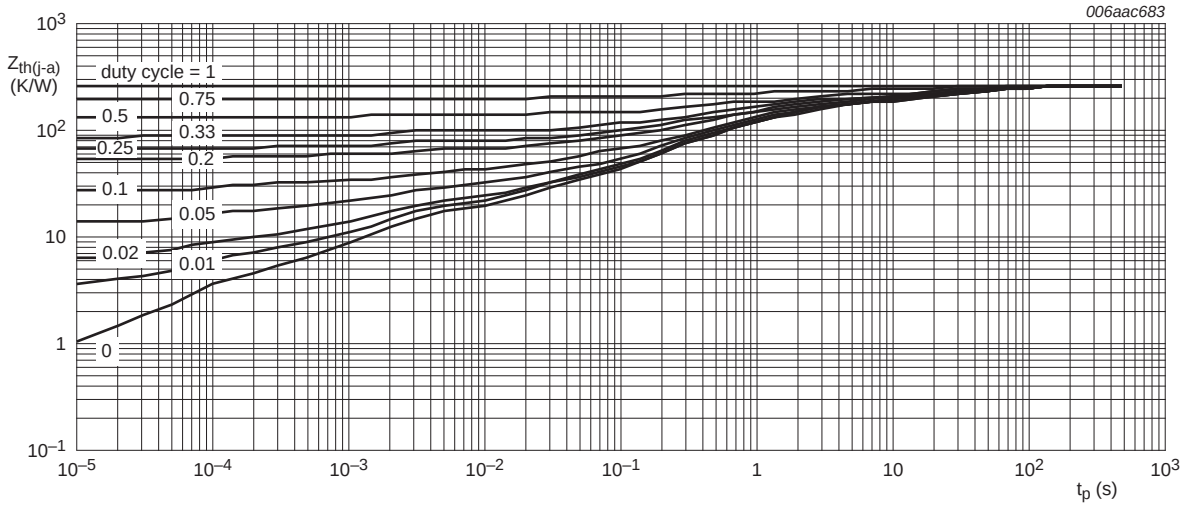
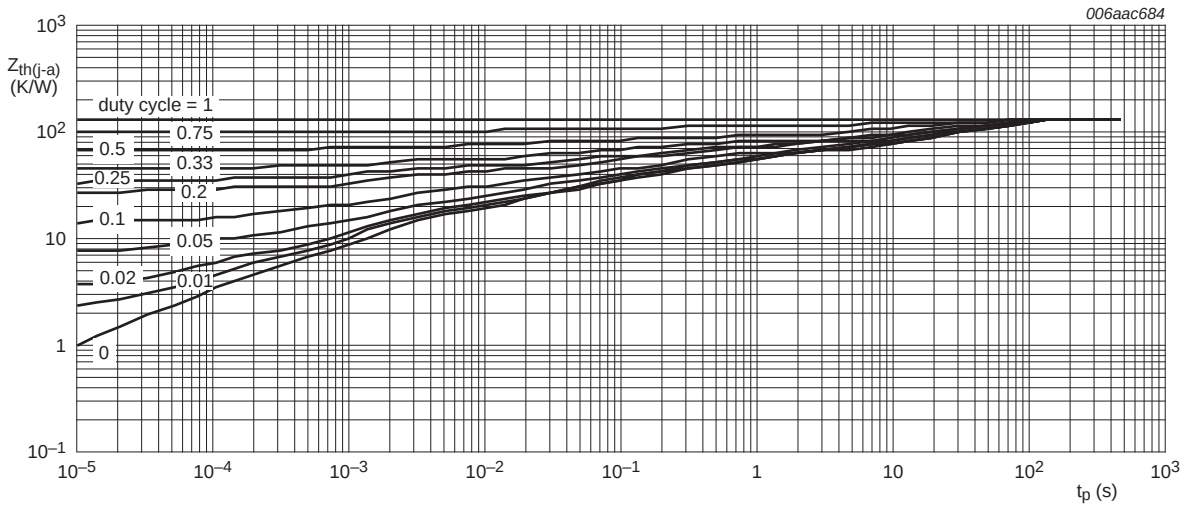


FR4 PCB, single-sided copper, standard footprint

Fig 10. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT1061; typical values



FR4 PCB, single-sided copper, mounting pad for collector 1 cm^2

Fig 11. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT1061; typical values

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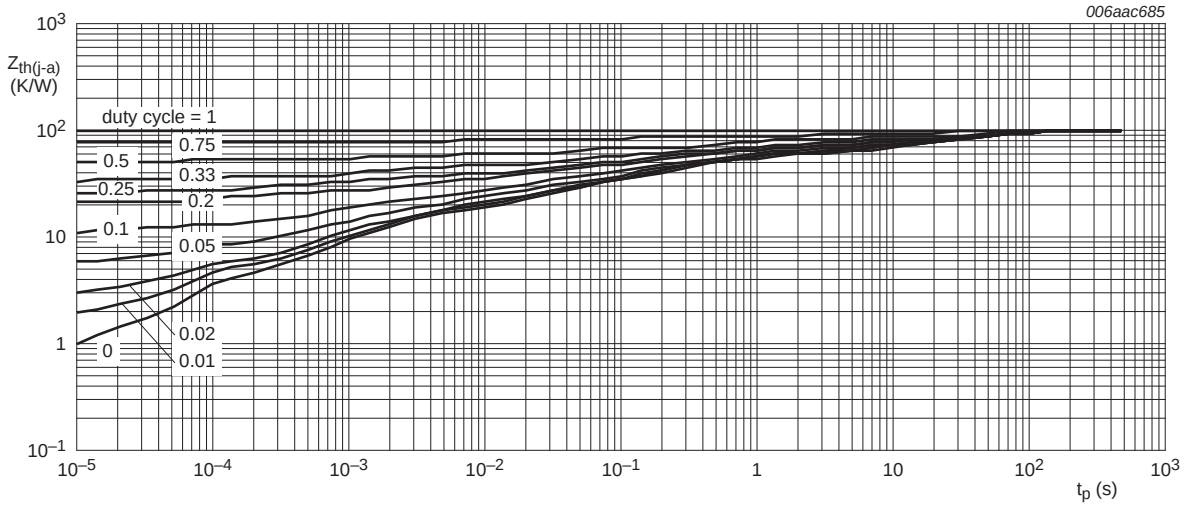
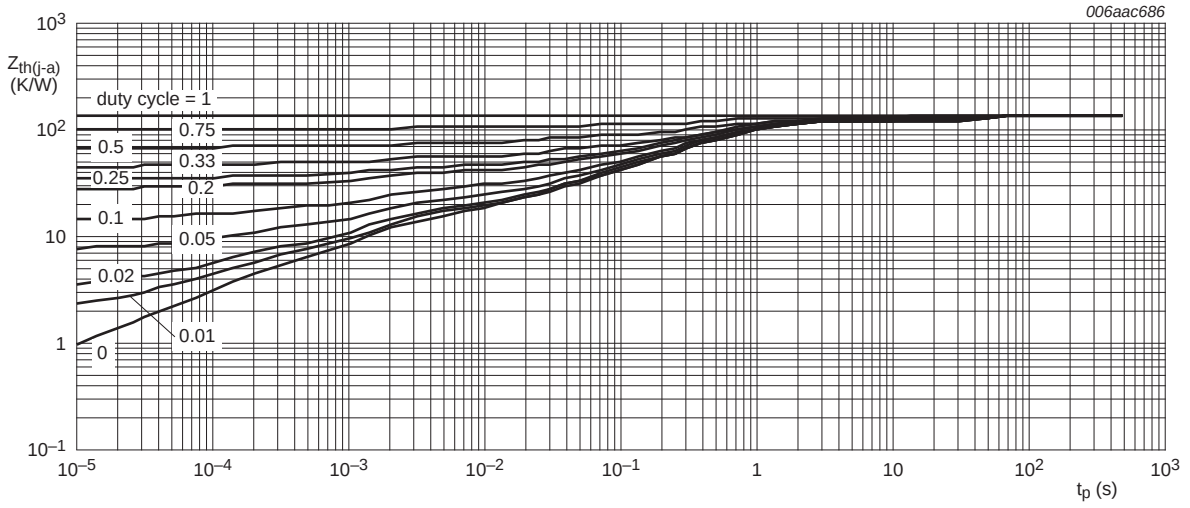


FR4 PCB, single-sided copper, mounting pad for collector 6 cm^2

Fig 12. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT1061; typical values



FR4 PCB, 4-layer copper, standard footprint

Fig 13. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT1061; typical values

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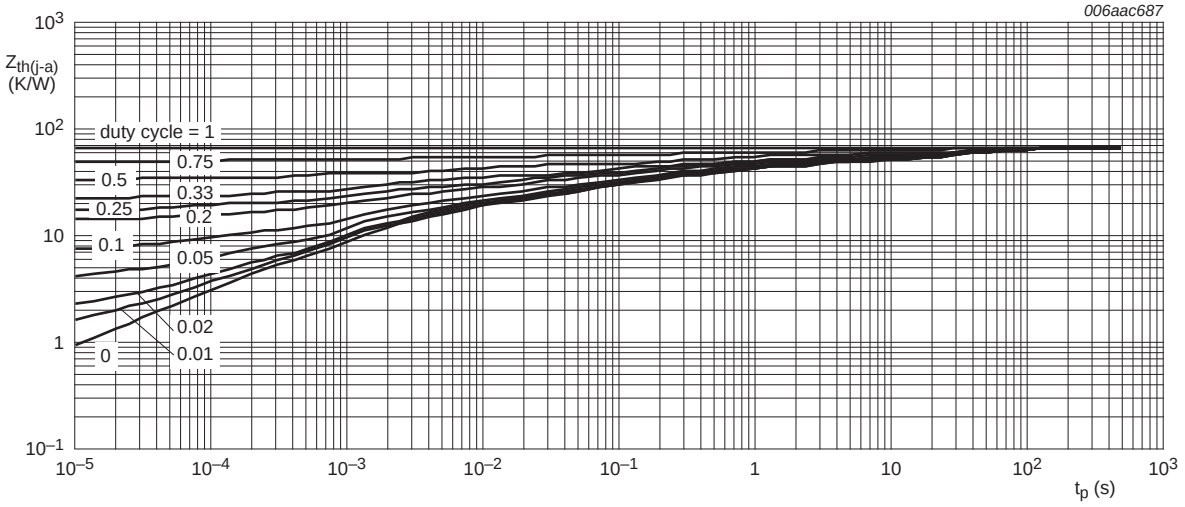

FR4 PCB, 4-layer copper, mounting pad for collector 1 cm^2

Fig 14. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT1061; typical values

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7. Characteristics

Table 8. Characteristics

T_{amb} = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
I_{CBO}	collector-base cut-off current	V_{CB} = 25 V; I_E = 0 A		-	-	100	nA
		V_{CB} = 25 V; I_E = 0 A; T_j = 150 °C		-	-	10	μA
I_{EBO}	emitter-base cut-off current	V_{EB} = 5 V; I_C = 0 A		-	-	100	nA
h_{FE}	DC current gain	V_{CE} = 10 V					
		I_C = 5 mA		50	-	-	
	DC current gain	V_{CE} = 1 V					
		I_C = 500 mA	[1]	85	-	375	
		I_C = 1 A	[1]	60	-	-	
		I_C = 2 A	[1]	40	-	-	
	DC current gain	V_{CE} = 1 V					
	h_{FE} selection -25	I_C = 500 mA	[1]	160	-	375	
V_{CEsat}	collector-emitter saturation voltage	I_C = 1 A; I_B = 100 mA	[1]	-	-	0.5	V
		I_C = 2 A; I_B = 200 mA	[1]	-	-	0.6	V
V_{BE}	base-emitter voltage	V_{CE} = 10 V; I_C = 5 mA	[1]	-	-	0.7	V
		V_{CE} = 1 V; I_C = 1 A	[1]	-	-	1	V
C_c	collector capacitance	V_{CB} = 10 V; I_E = i_e = 0 A; f = 1 MHz		-	22	-	pF
f_T	transition frequency	V_{CE} = 5 V; I_C = 50 mA; f = 100 MHz		40	170	-	MHz

[1] Pulse test: $t_p \leq 300$ μs; $\delta = 0.02$.

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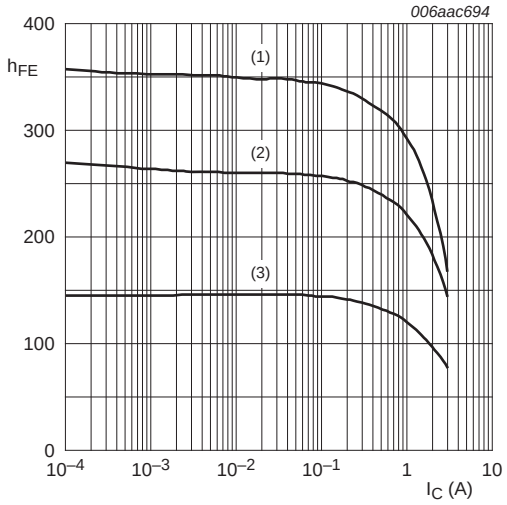


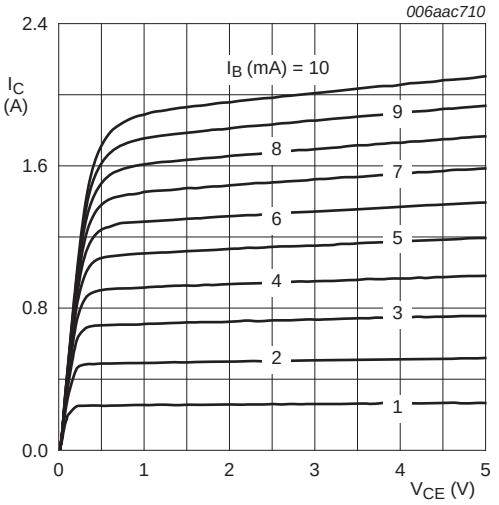
V_{CE} = 1 V

(1) T_{amb} = 100 °C

(2) T_{amb} = 25 °C

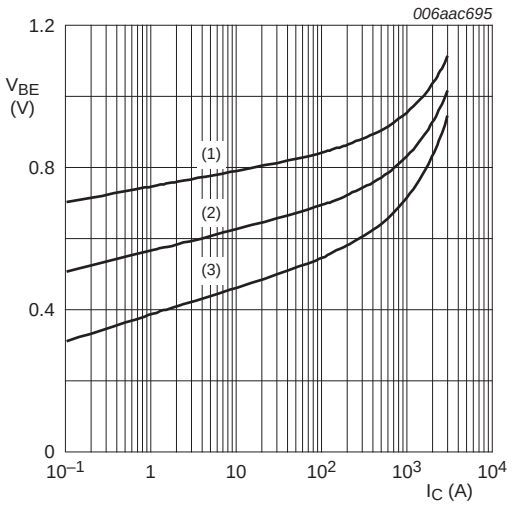
(3) T_{amb} = −55 °C

Fig 15. DC current gain as a function of collector current; typical values



T_{amb} = 25 °C

Fig 16. Collector current as a function of collector-emitter voltage; typical values



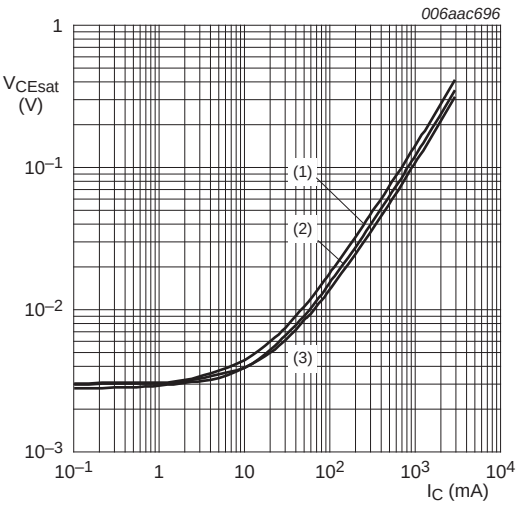
V_{CE} = 1 V

(1) T_{amb} = −55 °C

(2) T_{amb} = 25 °C

(3) T_{amb} = 100 °C

Fig 17. Base-emitter voltage as a function of collector current; typical values



I_C/I_B = 10

(1) T_{amb} = 100 °C

(2) T_{amb} = 25 °C

(3) T_{amb} = −55 °C

Fig 18. Collector-emitter saturation voltage as a function of collector current; typical values

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8. Test information

8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

9. Package outline

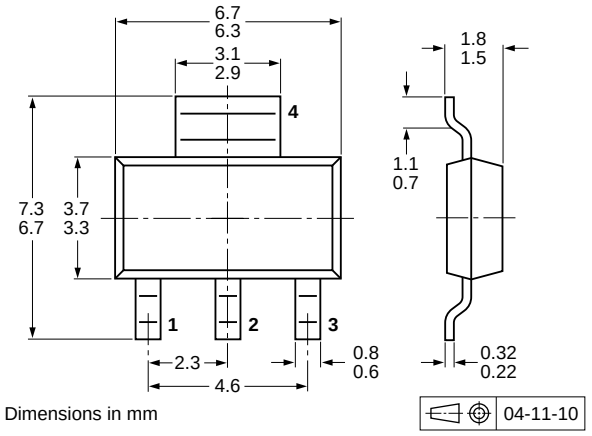

Fig 19. Package outline SOT223 (SC-73)

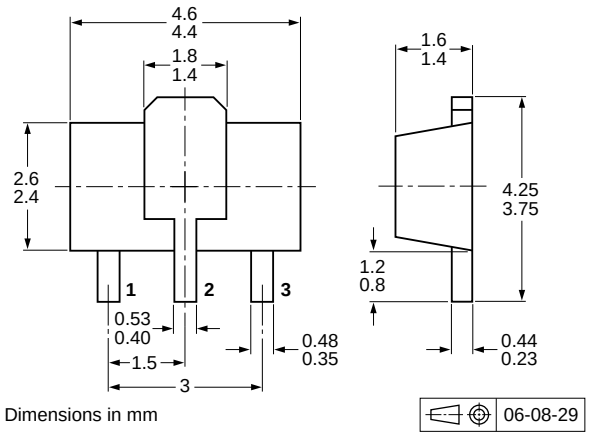

Fig 20. Package outline SOT89 (SC-62/TO-243)

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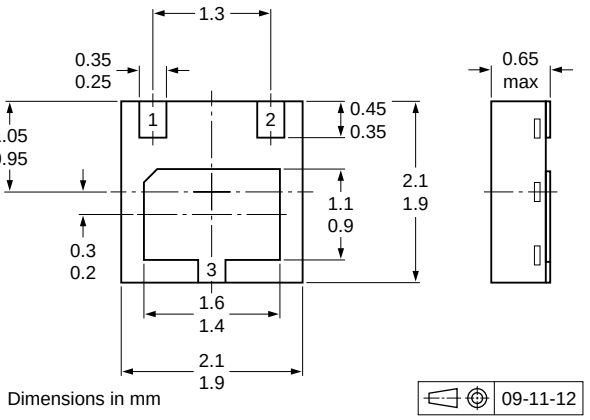

Fig 21. Package outline SOT1061 (HUSON3)

10. Packing information

Table 9. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.[1]

Type number[2]	Package	Description	Packing quantity		
			1000	3000	4000
BCP68	SOT223	8 mm pitch, 12 mm tape and reel	-115	-	-135
BC868	SOT89	8 mm pitch, 12 mm tape and reel; T1 [3]	-115	-	-135
		8 mm pitch, 12 mm tape and reel; T3 [4]	-146	-	-
BC68PA	SOT1061	4 mm pitch, 8 mm tape and reel	-	-115	-

[1] For further information and the availability of packing methods, see Section 14.

[2] Valid for all available selection groups.

[3] T1: normal taping

[4] T3: 90° rotated taping

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11. Soldering

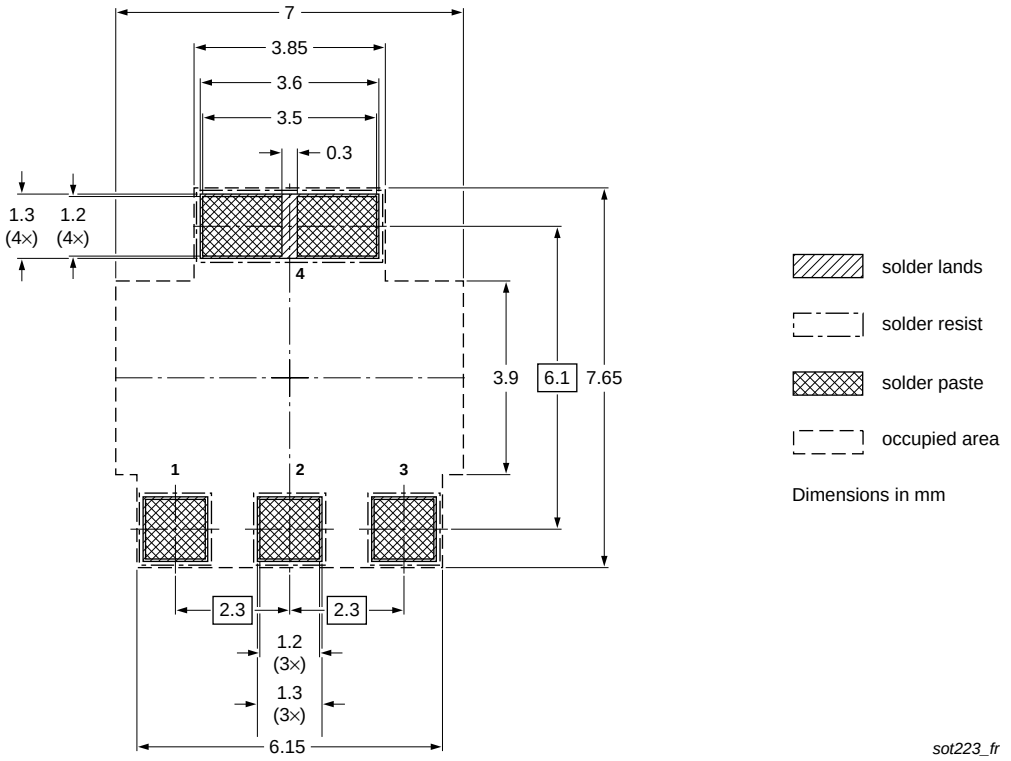

Fig 22. Reflow soldering footprint SOT223 (SC-73)

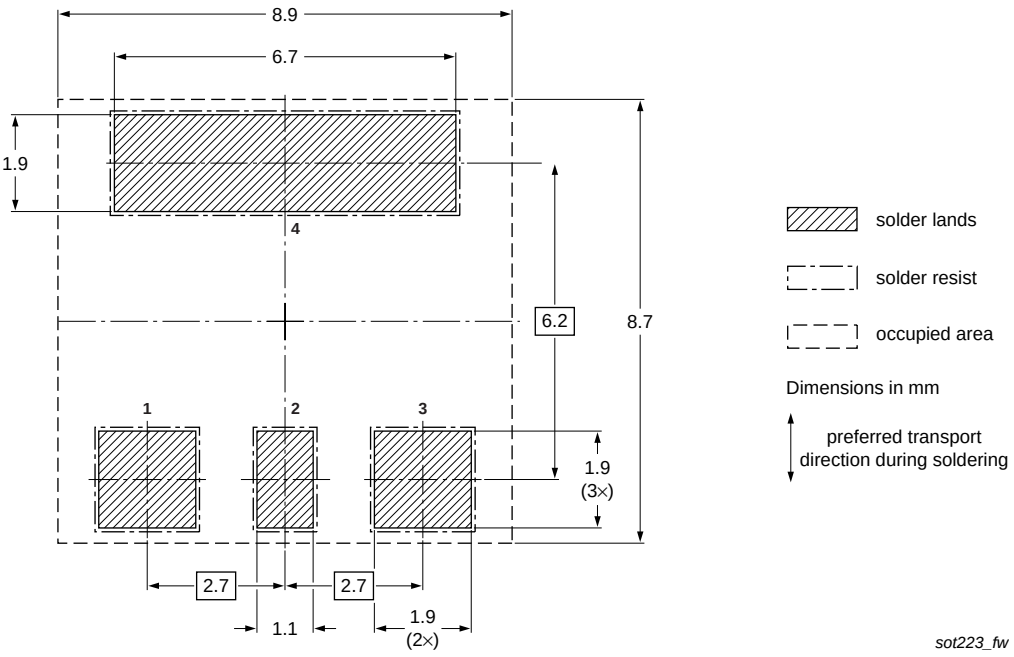

Fig 23. Wave soldering footprint SOT223 (SC-73)

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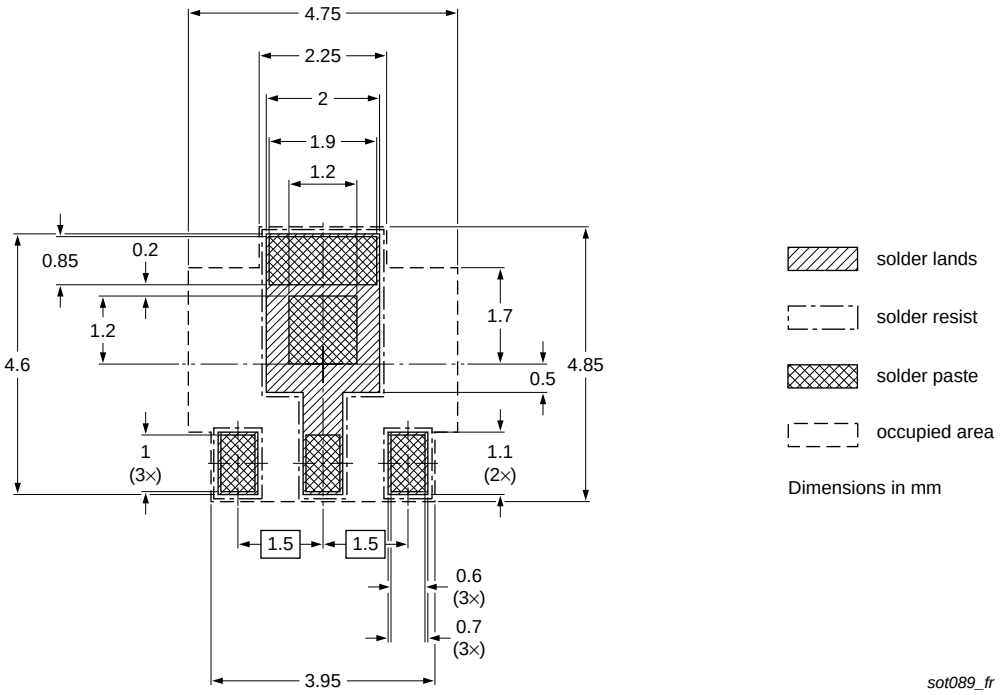

Fig 24. Reflow soldering footprint SOT89 (SC-62/TO-243)

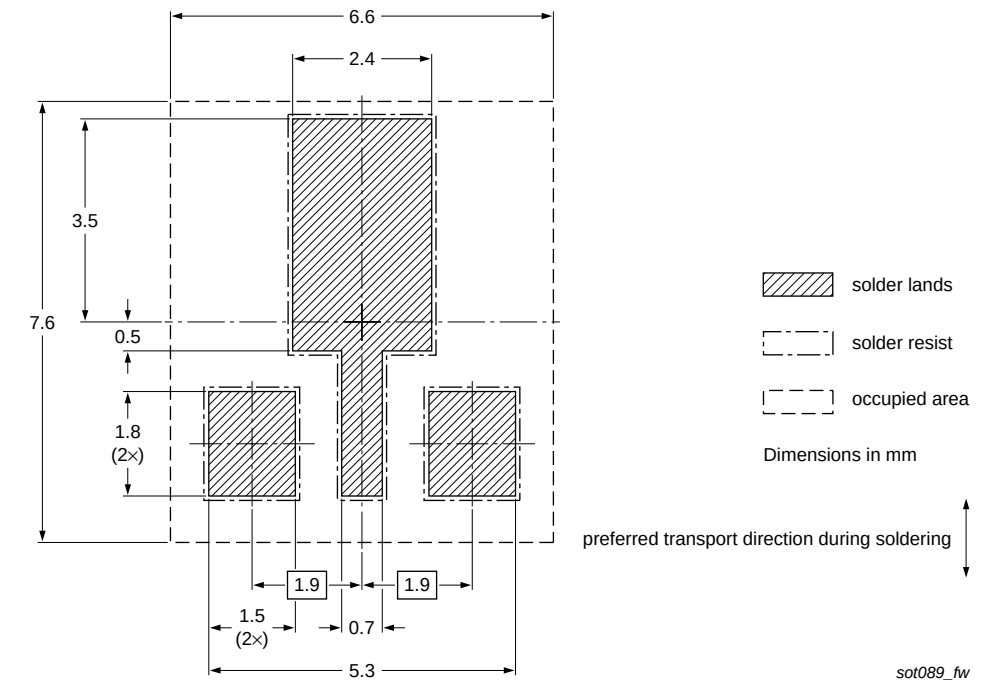

Fig 25. Wave soldering footprint SOT89 (SC-62/TO-243)

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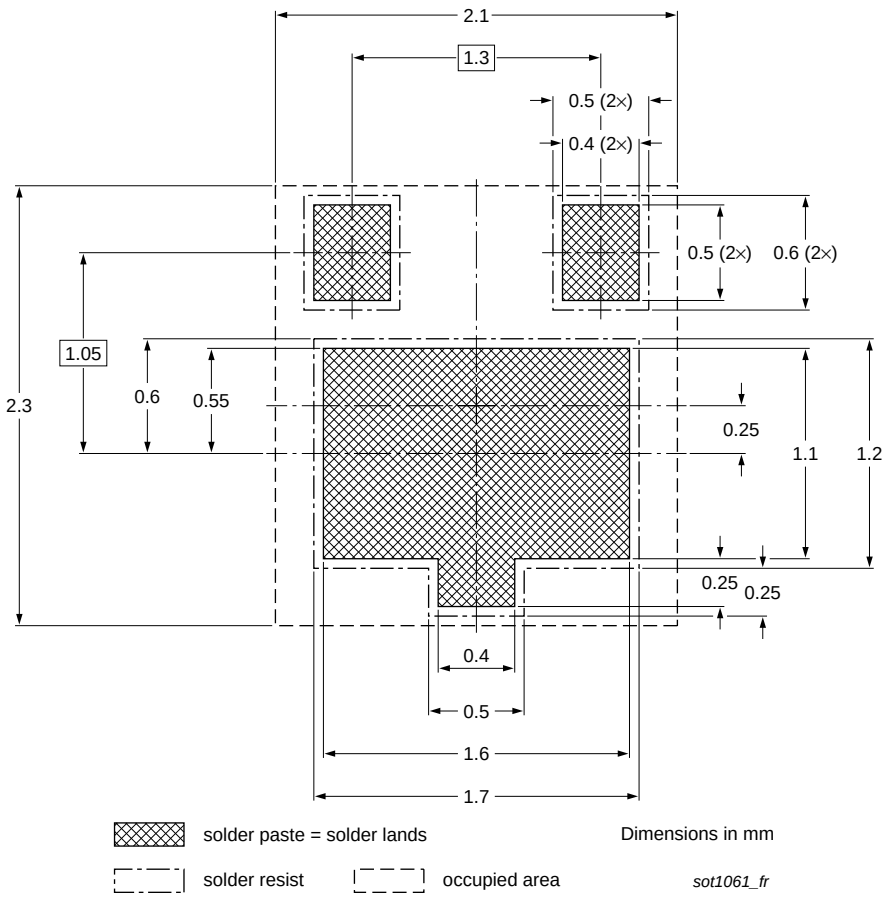

Reflow soldering is the only recommended soldering method.

Fig 26. Reflow soldering footprint SOT1061 (HUSON3)

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